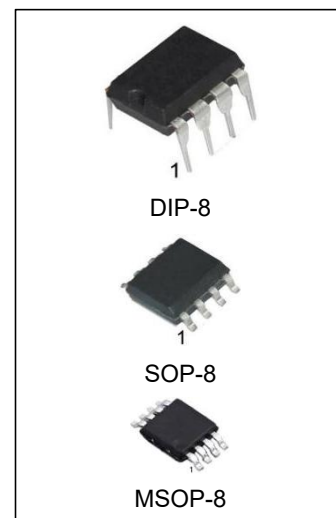


1 MHz Bandwidth Low Power Op Amp

Features

- 1 MHz Gain Bandwidth Product (typ.)
- Rail-to-Rail Input/Output
- Supply Voltage: 1.8V to 5.5V
- Supply Current: $I_Q = 100 \mu A$ (typ.)
- 90° Phase Margin (typ.)
- Temperature Range:
-Industrial: -40°C to +85°C
- Available in Single, Dual and Quad Packages



Ordering Information

DEVICE	Package Type	MARKING	Packing	Packing Qty
LMV932N	DIP-8	LMV932, V932	TUBE	2000pcs/Box
LMV932M/TR	SOP-8	LMV932, V932	REEL	2500pcs/Reel
LMV932MM/TR	MSOP-8	LMV932, V932	REEL	3000pcs/Reel

Description

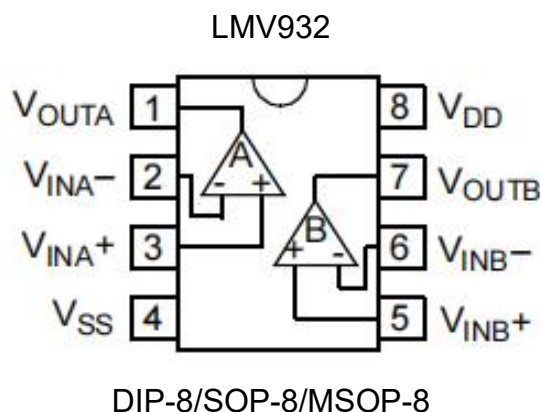
LMV932 operational amplifiers (op amps) is specifically designed for general-purpose applications. This family has a 1 MHz gain bandwidth product and 90° phase margin (typ.). It also maintains 45° phase margin (typ.) with 500 pF capacitive load. This family operates from a single supply voltage as low as 1.8V, while drawing 100 μ A (typ.) quiescent current. Additionally, the LM932 supports rail-to-rail input and output swing with a common mode input voltage range of $V_{DD} + 300$ mV to $V_{SS} - 300$ mV. This family of operational amplifiers is designed with Microchip's advanced CMOS process.

The LMV932 family is available in the industrial and extended temperature ranges. It also has a power supply range of 1.8V to 5.5V.

Applications

- Automotive
- Portable Equipment
- Photodiode Pre-amps
- Analog Filters
- Notebooks and PDAs
- Battery-Powered Systems

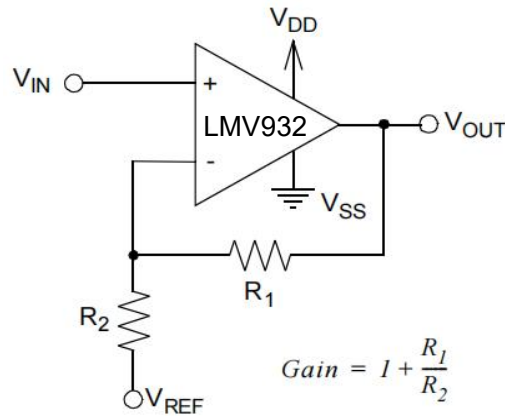
Package Types



PIN FUNCTION TABLE

Name	Function
V_{INA+} , V_{INB+}	Non-inverting Inputs
V_{INA-} , V_{INB-}	Inverting Inputs
V_{DD}	Positive Power Supply
V_{SS}	Negative Power Supply
V_{OUTA} , V_{OUTB}	Outputs

Typical Application



Absolute Maximum Ratings

Condition		Min	Max
$V_{DD} - V_{SS}$		7.0V	
All Inputs and Outputs		$V_{SS}-0.3V$	$V_{DD}+0.3V$
Difference Input Voltage		$ V_{DD}-V_{SS} $	
Output Short Circuit Current		continuous	
Current at Input Pins		-2mA	+2mA
Current at Output and Supply Pins		-30mA	+30mA
Storage Temperature		-65°C	+150°C
Maximum Junction Temperature (T_J)		-	+150°C
Lead Temperature (Soldering, 10 seconds)		-	260°C
ESD Protection On All Pins	HBM	$\geq 4KV$	
	MM	200V	

Notice: Stresses above those listed under "Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operational listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

AC ELECTRICAL SPECIFICATIONS

Electrical Characteristics:

Unless otherwise indicated, $T_A = +25^{\circ}\text{C}$, $V_{DD} = +1.8$ to 5.5V , $V_{SS} = \text{GND}$, $V_{CM} = V_{DD}/2$, $V_{OUT} \approx V_{DD}/2$, $R_L = 10\text{ k}\Omega$ to $V_{DD}/2$, and $C_L = 60\text{ pF}$.

Parameters	Sym	Min	Typ	Max	Units	Conditions
AC Response						
Gain Bandwidth Product	GBWP	—	1.0	—	MHz	
Phase Margin	PM	—	90	—	°	$G = +1$
Slew Rate	SR	—	0.6	—	$\text{V}/\mu\text{s}$	
Noise						
Input Noise Voltage	Eni	—	6.1	—	$\mu\text{Vp-p}$	$f = 0.1\text{ Hz to }10\text{ Hz}$
Input Noise Voltage Density	eni	—	28	—	$\text{nV}/\sqrt{\text{Hz}}$	$f = 1\text{ kHz}$
Input Noise Current Density	ini	—	0.6	—	$\text{fA}/\sqrt{\text{Hz}}$	$f = 1\text{ kHz}$

TYPICAL PERFORMANCE CURVES

Unless otherwise indicated, $T_A = +25^\circ\text{C}$, $V_{DD} = +1.8\text{V}$ to $+5.5\text{V}$, $V_{SS} = \text{GND}$, $V_{CM} = V_{DD}/2$, $V_{OUT} \approx V_{DD}/2$, $R_L = 10\text{ k}\Omega$ to $V_{DD}/2$, and $C_L = 60\text{ pF}$.

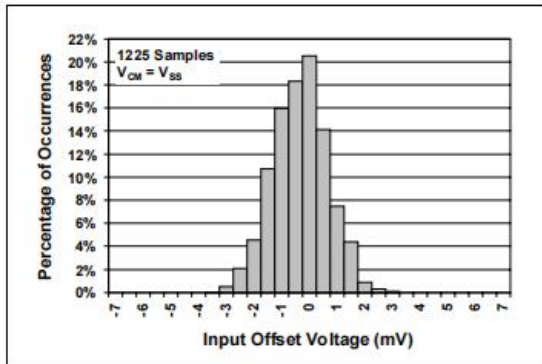


FIGURE 2-1: Input Offset Voltage Histogram.

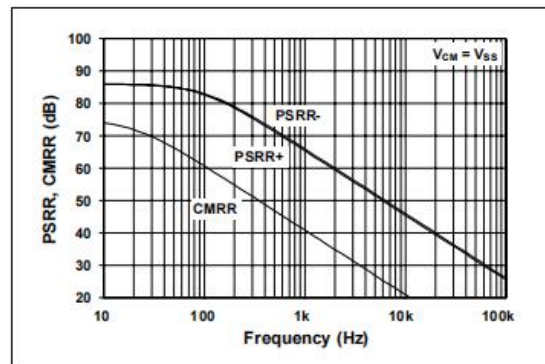


FIGURE 2-2: PSRR, CMRR vs. Frequency.

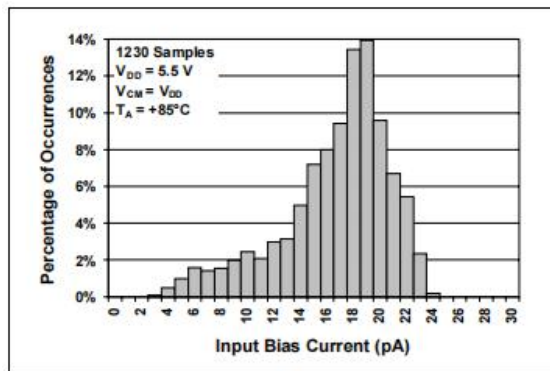


FIGURE 2-3: Input Bias Current at $+85^\circ\text{C}$ Histogram.

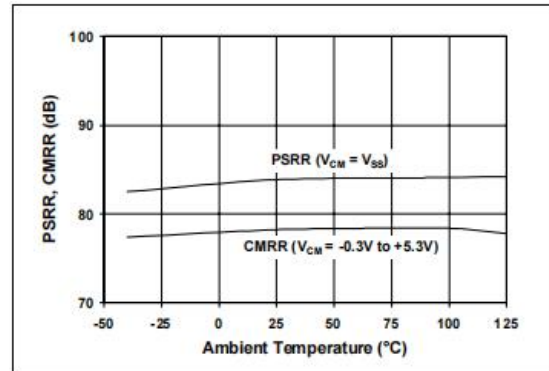


FIGURE 2-4: CMRR, PSRR vs. Ambient Temperature.

Note: Unless otherwise indicated, $T_A = +25^\circ\text{C}$, $V_{DD} = +1.8\text{V}$ to $+5.5\text{V}$, $V_{SS} = \text{GND}$, $V_{CM} = V_{DD}/2$, $V_{OUT} \approx V_{DD}/2$, $R_L = 10\text{ k}\Omega$ to $V_{DD}/2$, and $C_L = 60\text{ pF}$.

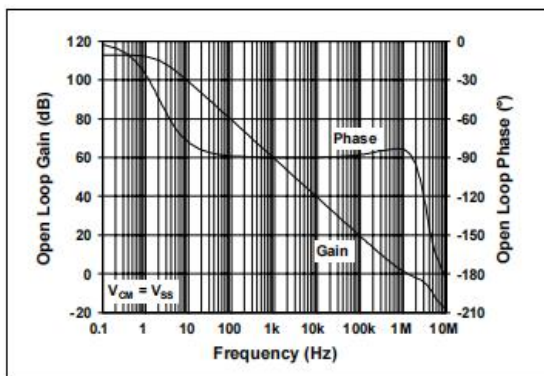


FIGURE 2-5: Open-Loop Gain, Phase vs. Frequency.

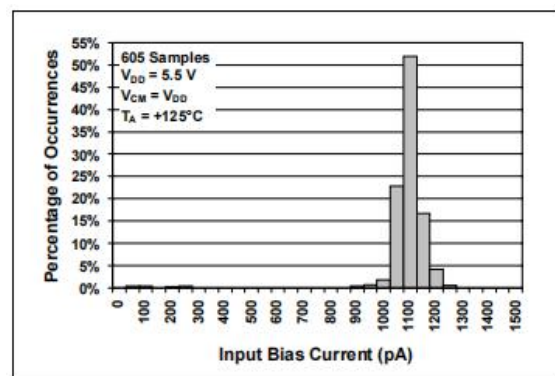


FIGURE 2-6: Input Bias Current at $+125^\circ\text{C}$ Histogram.

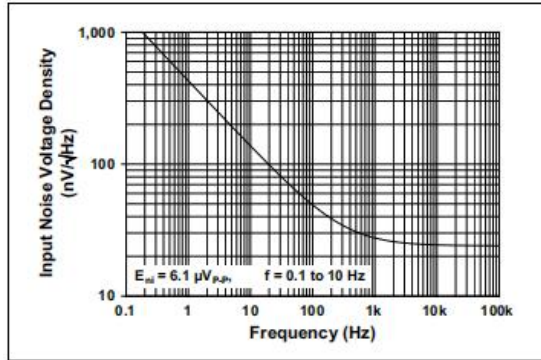


FIGURE 2-7: Input Noise Voltage Density vs. Frequency.

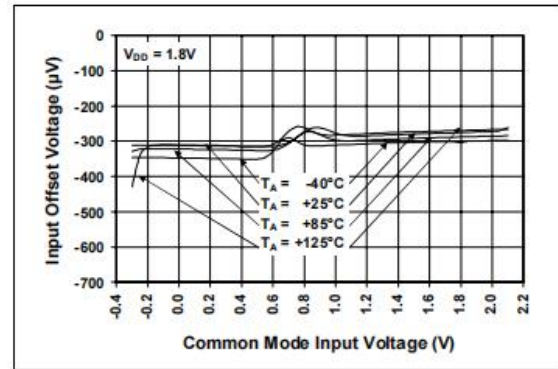


FIGURE 2-8: Input Offset Voltage vs. Common Mode Input Voltage at $V_{DD} = 1.8V$.

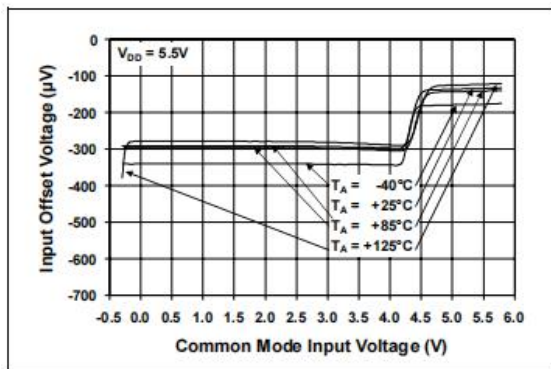


FIGURE 2-9: Input Offset Voltage vs. Common Mode Input Voltage at $V_{DD} = 5.5V$.

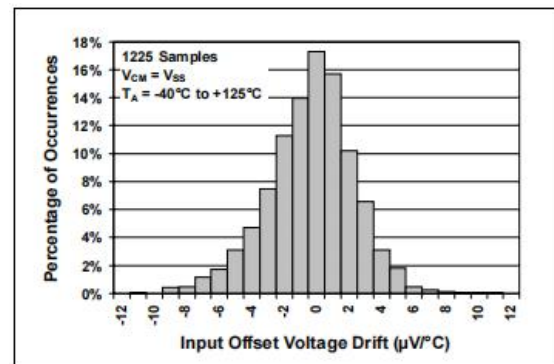


FIGURE 2-10: Input Offset Voltage Drift Histogram.

Note: Unless otherwise indicated, $T_A = +25^\circ\text{C}$, $V_{DD} = +1.8V$ to $+5.5V$, $V_{SS} = \text{GND}$, $V_{CM} = V_{DD}/2$, $V_{OUT} \approx V_{DD}/2$, $R_L = 10\text{ k}\Omega$ to $V_{DD}/2$, and $C_L = 60\text{ pF}$.

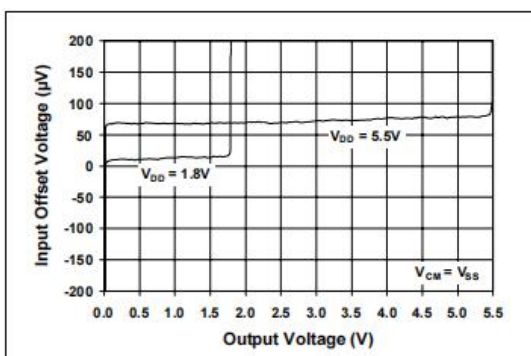


FIGURE 2-11: Input Offset Voltage vs. Output Voltage.

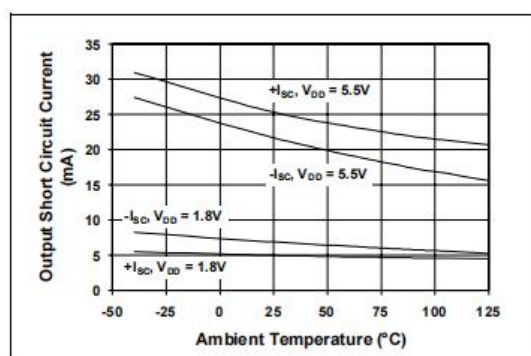


FIGURE 2-12: Output Short-Circuit Current vs. Ambient Temperature.

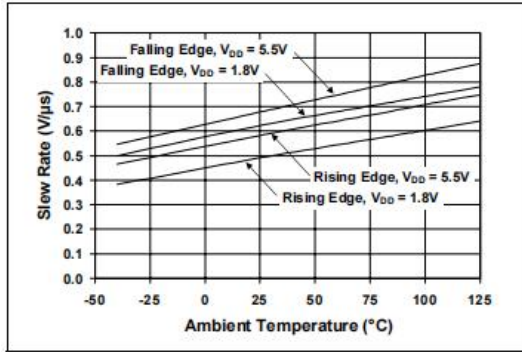


FIGURE 2-13: Slew Rate vs. Ambient Temperature.

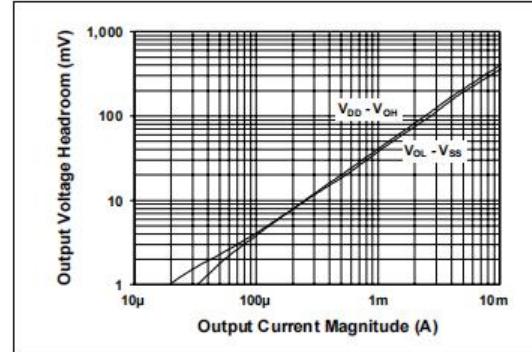


FIGURE 2-14: Output Voltage Headroom vs. Output Current Magnitude.

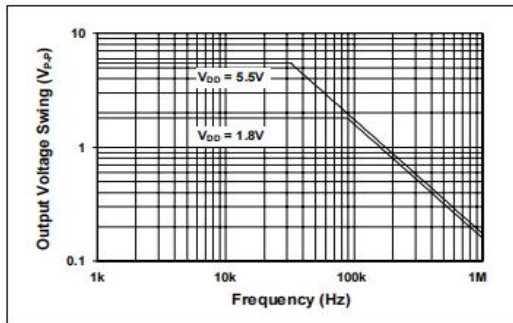


FIGURE 2-15: Output Voltage Swing vs. Frequency

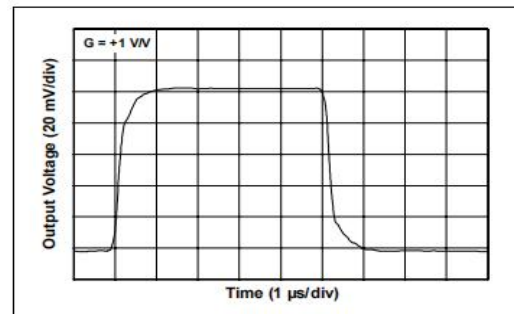


FIGURE 2-16: Small Signal Non-Inverting Pulse Response.

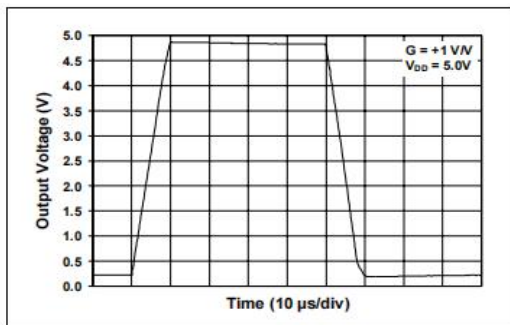


FIGURE 2-17: Large Signal Non-Inverting Pulse Response.

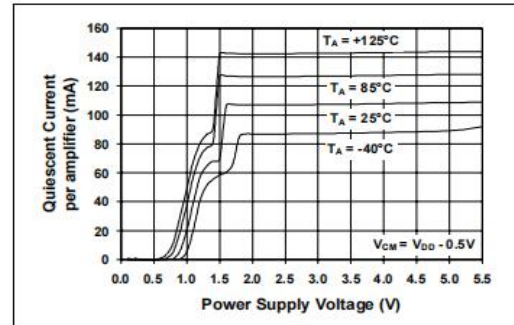
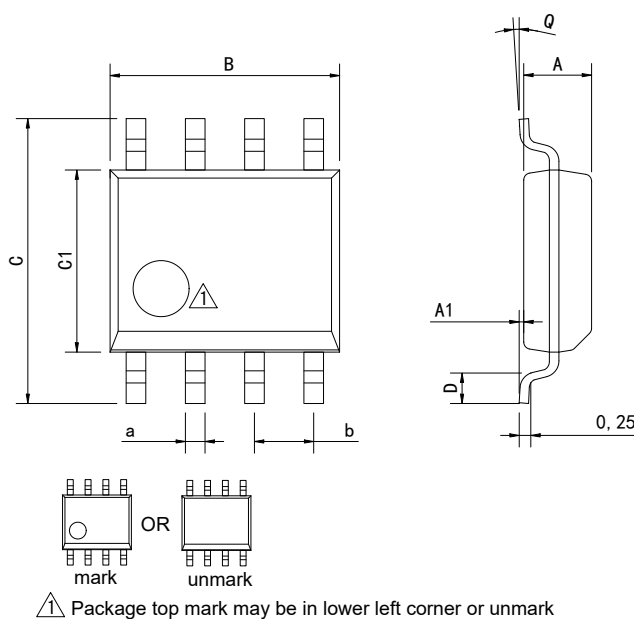


FIGURE 2-18: Quiescent Current vs. Power Supply Voltage.

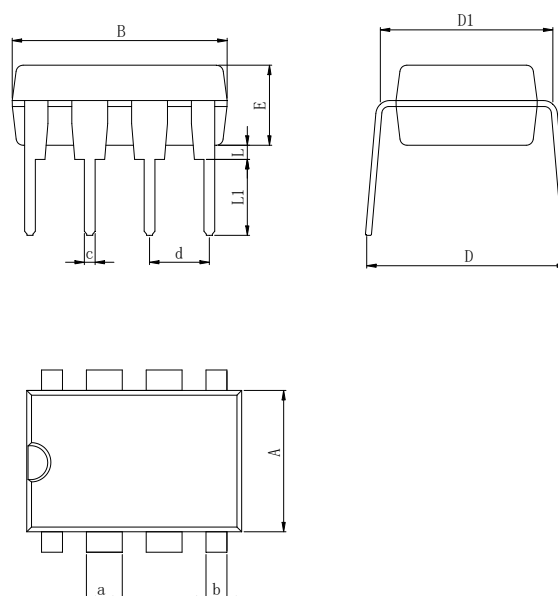
Physical Dimensions

SOP-8



Dimensions In Millimeters(SOP-8)									
Symbol:	A	A1	B	C	C1	D	Q	a	b
Min:	1.35	0.05	4.90	5.80	3.80	0.40	0°	0.35	1.27 BSC
Max:	1.55	0.20	5.10	6.20	4.00	0.80	8°	0.45	

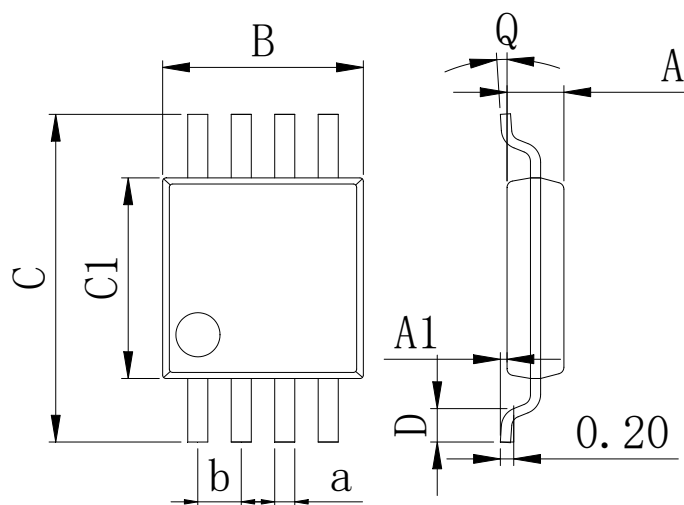
DIP-8



Dimensions In Millimeters(DIP-8)											
Symbol:	A	B	D	D1	E	L	L1	a	b	c	d
Min:	6.10	9.00	8.10	7.42	3.10	0.50	3.00	1.50	0.85	0.40	2.54 BSC
Max:	6.68	9.50	10.9	7.82	3.55	0.70	3.60	1.55	0.90	0.50	

Physical Dimensions

MSOP-8



Dimensions In Millimeters(MSOP-8)									
Symbol:	A	A1	B	C	C1	D	Q	a	b
Min:	0.80	0.05	2.90	4.75	2.90	0.35	0°	0.25	0.65 BSC
Max:	0.90	0.20	3.10	5.05	3.10	0.75	8°	0.35	

Revision History

REVISION NUMBER	DATE	REVISION	PAGE
V1.0	2014-6	New	1-12
V1.1	2017-8	Update encapsulation type、Updated DIP-8 dimension	1、 9
V1.2	2024-11	Add a model marking name、 Update Lead Temperature	1、 3
V1.3	2025-12	Update important statements、 Update sop-8 Dimension drawing	9、 12

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